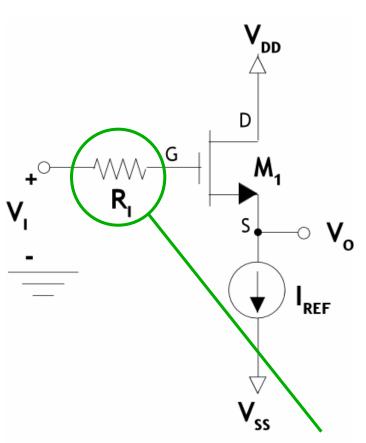


Outline of Chapter 4

- 1- Intro to MOS Field Effect Transistor (MOSFET)
- 2- NMOS FET
- 3- PMOS FET
- 4- DC Analysis of MOSFET Circuits
- 5- MOSFET Amplifier
- 6- MOSFET Small Signal Model
- 7- MOSFET Integrated Circuits
- <u>8- CSA, CGA, CDA</u>
- 9- CMOS Inverter & MOS Digital Logic

McGill Department of Electrical and Computer Engineering **Common Drain Amplifier (CDA)**



- A nMOS current mirror is used as I_{REF} including the output resistance.
- Voltage signal source DCcoupled to gate terminal
 - Drain terminal held at a DC voltage
- Since source terminal not at signal ground, Body effect exists

 R_{I} is the resistance from previous stage

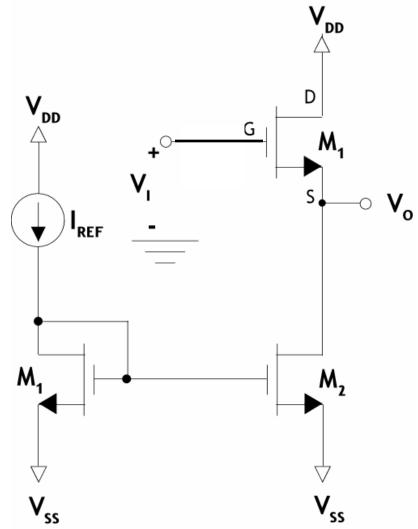




- Replace with a "real" current source including output resistance r_{o2}
- No problem including AC CLM
- Two types of analysis:

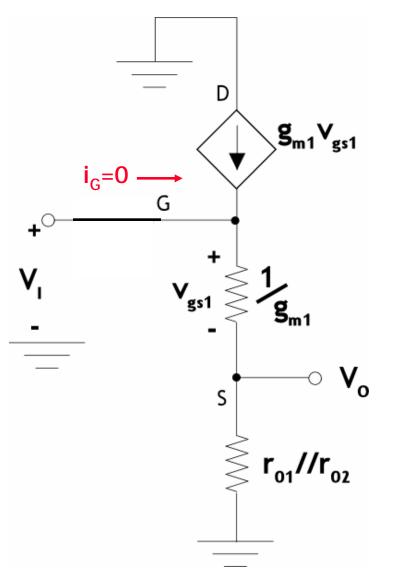
Neglect AC Body-Effect

Use AC Body-Effect





CDA Without Body Effect



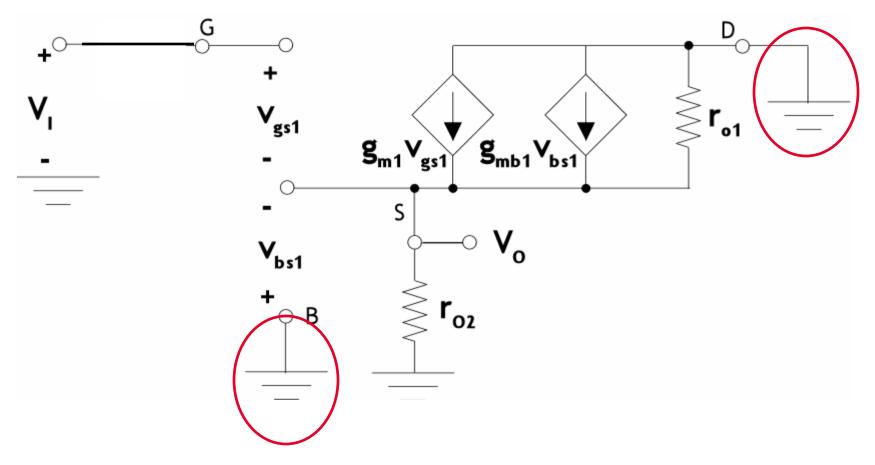
$$A_{V} = \frac{v_{o}}{v_{I}} = \frac{r_{o2} \| r_{o1}}{r_{o2} \| r_{o1} + \frac{1}{g_{m1}}}$$

$$R_{IN} \Rightarrow \infty$$

$$R_{OUT} = r_{o1} \| r_{o2} \| \frac{1}{g_{m1}} \|$$

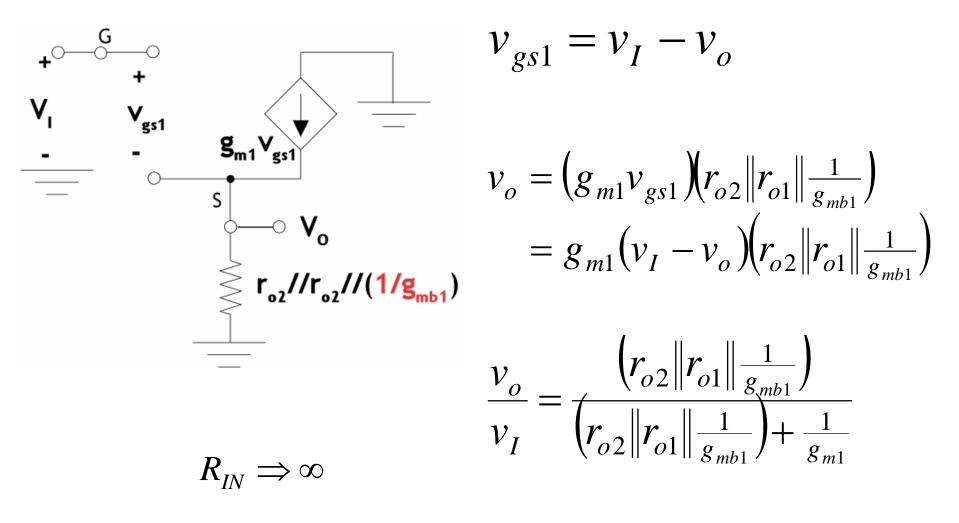


CDA With Body Effect





CDA With Body Effect



CDA With Body Effect - R_{OUT}

Short input voltage source $v_{gs1} = -v_x$ $v_x = (g_{m1}v_{gs1} + i_x)(r_{o2}||r_{o1}|| \frac{1}{g_{mb1}})$ S $\frac{1}{v_{x}} R_{OUT} = \frac{v_{x}}{i_{x}} = \frac{r_{o2} \|r_{o1}\| \frac{1}{g_{mb1}}}{1 + g_{m1} (r_{o2} \|r_{o1}\| \frac{1}{g_{mb1}})}$ By source-absorption:

 $R_{OUT} = r_{o1} // r_{o2} // (1 / g_{m1}) // (1 / g_{mb1}))$



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V_{DD}

S

D

D

G

G

V_I C

CMOS Inverter

- MOSFETs can act as almost ideal current switches with symmetric VTCs.
- Matching of M_P and M_N : $|V_{tP}| = V_{tN} = V_t$
- Since typically k[']_P is 2-3 times smaller than k[']_n, the widths of the transistors are used to compensate:

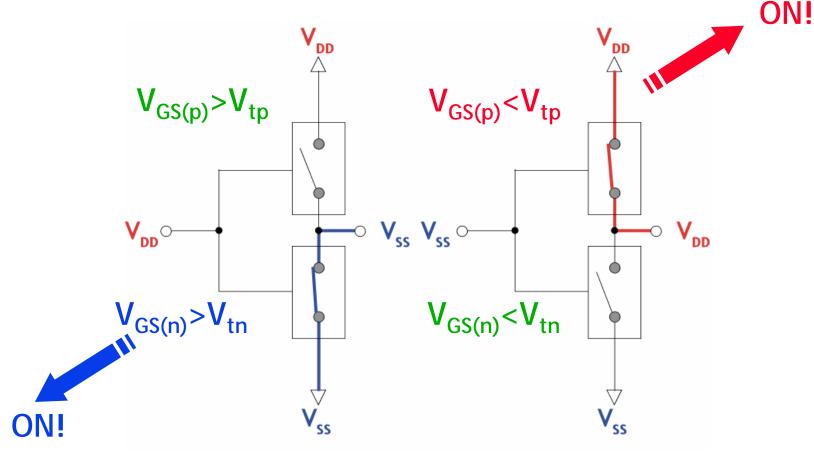
$$W_P = 3W_N \quad \square \qquad > \quad k'_p \frac{W_P}{L_P} = k'_n \frac{W_N}{L_N}$$

 This is definition of matched devices; equal current driving and sinking capabilities when charging & discharging capacitive loads





CMOS Inverter – Operation

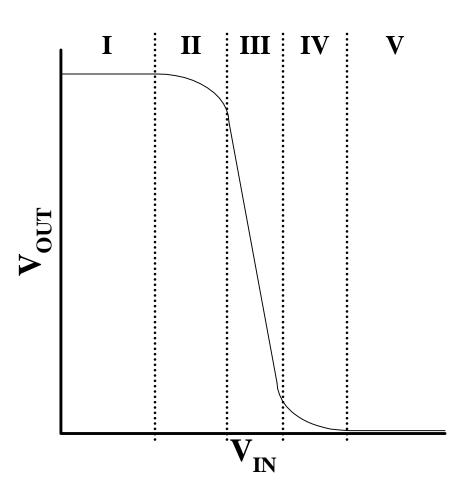


nMOS transistor pulls output voltage to the most negative rail. pMOS transistor pulls output voltage to the most positive rail. MOSFETs 10



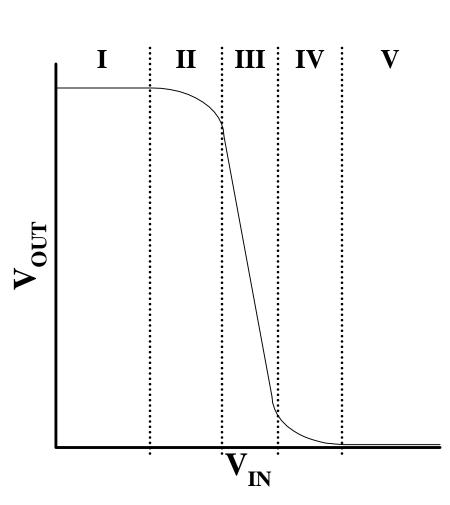
Inverter VTC

- Region I: $V_{IN} < V_t$
 - M_N cutoff, M_P in triode
 - Low-resistance path from V_{DD} to V_{OUT} pulls output high
 - No current flow
- Region II: $V_{IN} > V_t$
 - M_N enters saturation
 - M_P still in triode
 - Current flows,
 V_{OUT} starts to fall
- Region III:
 - High-gain region
 - M_N & M_P saturated
 - VTC slope = gain $_{M}$



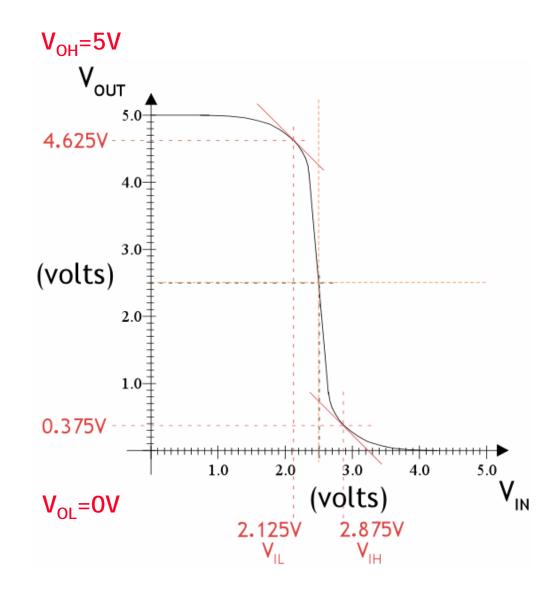


Inverter VTC



- Region IV:
 - M_N enters triode
 - M_P still in saturation
- Region V: $V_{IN} > V_{DD} V_t$
 - M_P cutoff, M_N in triode
 - Low-resistance path from
 V_{OUT} to ground pulls output low
 - No current flow

VTC Characteristics



- A matched inverter has symmetric voltage transfer characteristic.
- V_{OL} and V_{OH} are defined as 0V and 5V respectively.
- V_{IH} and V_{IL} defined as location where VTC slope = -1
 - V_{IL} is in region II
 - V_{IH} is in region IV

Finding V_{IH} – Matched Devices

• In region IV, M_P saturated, M_N in triode:

$$k_{P} \underbrace{W_{N}}_{N} \left[(V_{IN} - V_{t}) V_{OUT} - \frac{1}{2} V_{OUT}^{2} \right] = \frac{1}{2} k_{P} \underbrace{W_{P}}_{N} (V_{IN} - V_{DD} + V_{t})^{2}$$

$$(V_{IN} - V_t)V_{OUT} - \frac{1}{2}V_{OUT}^2 = \frac{1}{2}(V_{IN} - V_{DD} + V_t)^2$$
 (1)

• $V_{IN} = V_{IH}$ when $\frac{\partial V_{OUT}}{\partial V_{IN}} = -1$.: Take derivative wrt V_{IN}

$$V_{OUT} + \left(V_{IN} - V_t\right) \frac{\partial V_{OUT}}{\partial V_{IN}} - V_{OUT} \frac{\partial V_{OUT}}{\partial V_{IN}} = \left(V_{IN} - V_{DD} + V_t\right)$$

• Substitute $V_{IN} = V_{IH}$ & simplify to get: $V_{OUT} = V_{IH} - \frac{V_{DD}}{2}$

Finding V_{IH} – Matched Devices

• Take result for V_{OUT} when $V_{IN} = V_{IH}$

$$V_{OUT} = V_{IH} - \frac{V_{DD}}{2}$$

• Substitute into ①

$$\left(V_{IH} - V_t\right)\left(V_{IH} - \frac{V_{DD}}{2}\right) - \frac{1}{2}\left(V_{IH} - \frac{V_{DD}}{2}\right)^2 = \frac{1}{2}\left(V_{IH} - V_{DD} + V_t\right)^2$$

• Solving for V_{IH} , get: $V_{IH} = \frac{1}{8} (5V_{DD} - 2V_t)$

Finding V_{IL} – Matched Devices

- Can use similar procedure to find V_{IL}
 - Write equations for region II operation: M_P in triode, M_N in saturation
 - Solve for V_{OUT} when $V_{IN} = V_{IL}$ and substitute back into equations and solve for V_{IL}

$$V_{IL} = \frac{1}{8} \left(3V_{DD} + 2V_t \right)$$

- Result:
- Alternatively, can find V_{IL} using symmetry of VTC because V_{IL} and V_{IH} are symmetric about $V_{DD}/2$

$$V_{IH} - \frac{V_{DD}}{2} = \frac{V_{DD}}{2} - V_{IL}$$

Noise Margins

NM_H, High Noise Margin Definition:

$$NM_{H} = V_{OH} - V_{IH} = V_{DD} - V_{IH} \qquad V_{IH} = \frac{1}{8} (5V_{DD} - 2V_{t})$$
$$NM_{H} = V_{OH} - V_{IH} = \frac{1}{8} (3V_{DD} + 2V_{t})$$

NM_L: Low Noise Margin Definition:

$$NM_{L} = V_{IL} - V_{OL} = V_{IL} - 0 \qquad V_{IL} = \frac{1}{8} (3V_{DD} + 2V_{t})$$
$$NM_{L} = V_{IL} - V_{OL} = \frac{1}{8} (3V_{DD} + 2V_{t})$$

Conclusion: NMs equal for matched devices (Problem 4.107) MOSFETs 17

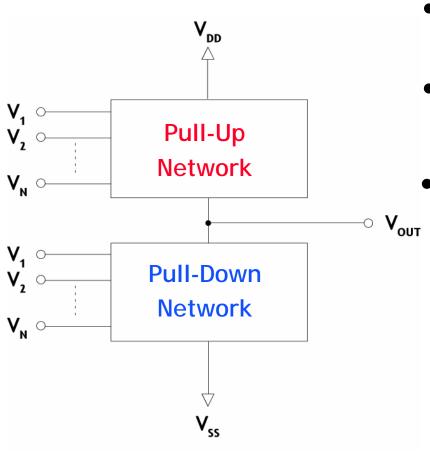
Mismatched Inverter Characteristics

• For mismatched devices:

$$\left|V_{tp}\right| \neq V_{tn}$$
 $k'_{p} \frac{W_{P}}{L_{P}} \neq k'_{n} \frac{W_{N}}{L_{N}}$

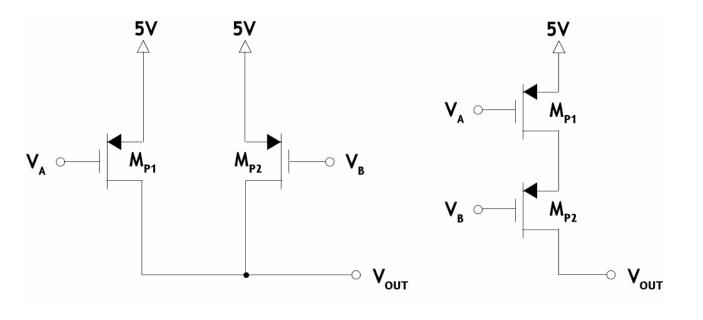
- VTC not symmetric any longer
- V_{IL} and V_{IH} can be found using same approach as before, with more algebra
- Resulting VTC noise margins will not be equal, but V_{OH} and V_{OL} will be unchanged

Structure of CMOS Logic-Gates



- P-U-N: pull-up network (PMOS transistors)
- **P-D-N: pull-down network** (NMOS transistors)
- P-U-N & P-D-N almost invariably made *complementary* networks
 - i.e. series-connected transistors in one network are parallelconnected in the other & vice versa
 - Facilitates formal design and logic synthesis techniques MOSFETs 19

Basic Pull-Up Structures



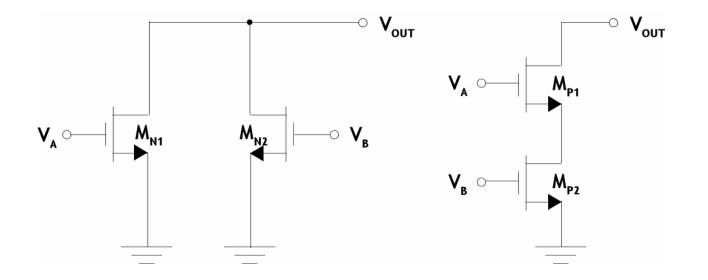
Parallel Structure $V_A or V_B$ is low

$$V_{OUT} = \overline{V_A} + \overline{V_B}$$

Serial Structure V_{OUT} is high when *either* V_{OUT} is high when *both* V_A and $V_{\rm B}$ are low

$$V_{OUT} = \overline{V_A} \cdot \overline{V_B}$$

Basic Pull-Down Structures



Parallel Structure $V_A or V_B$ is high

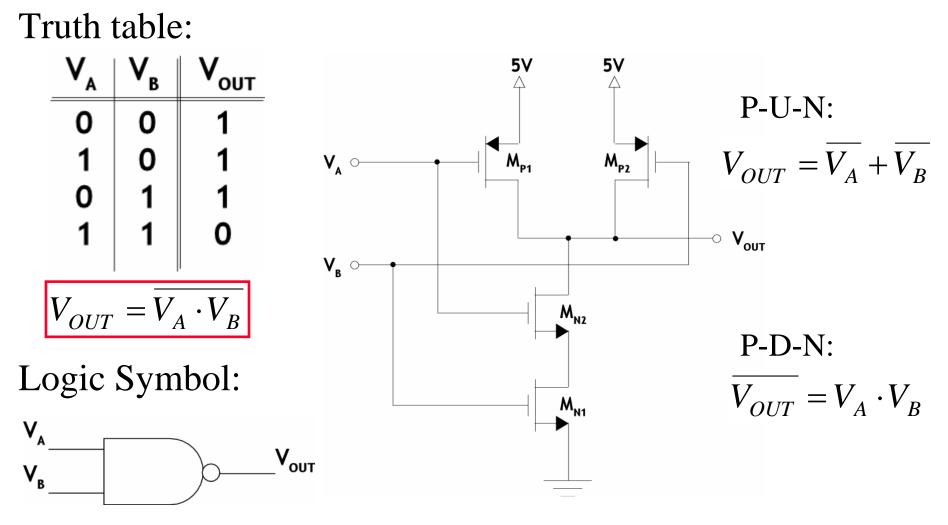
$$\overline{V_{OUT}} = V_A + V_B$$

Serial Structure V_{OUT} is low when *either* V_{OUT} is low when *both* V_A and $V_{\rm B}$ are high

$$\overline{V_{OUT}} = V_A \cdot V_B$$

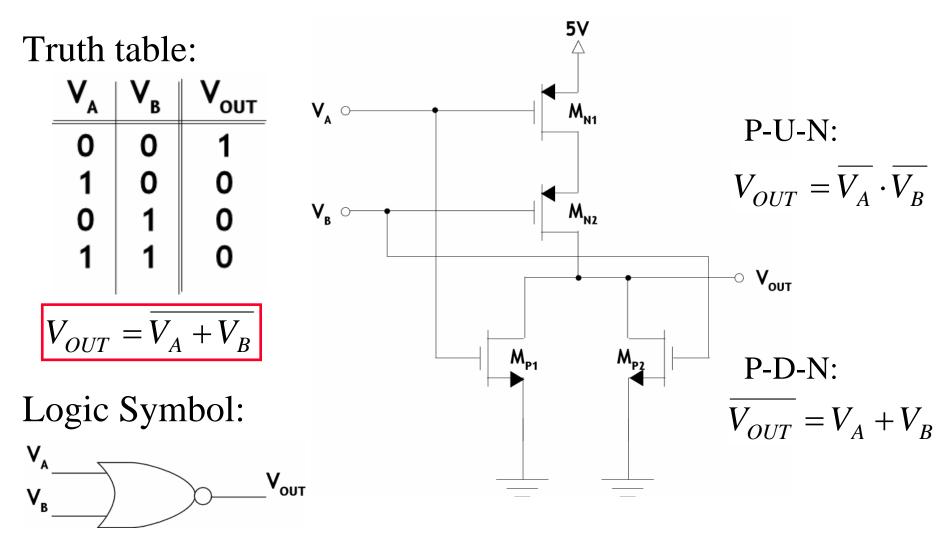


2-Input CMOS NAND Gate





2-Input CMOS NOR Gate



Outline of Chapter 4, Sections 4.8-4.9

- 1- High-Frequency Model of MOSFET
- 2- Frequency Response of CSA
- Note: Frequency response of CGA and CDA are covered in EC2

High-Frequency Model

- The small signal model discussed so far didn't include internal capacitances and resulted in constant gain without accounting for frequency changes.
- Internal capacitances:
 - The gate capacitive (Cox) effect is modeled by three capacitors Cgs, Cgd and Cgb
 - The source-body and drain-body depletion layer capacitances: Reverse biased pn junctions



Gate Capacitive Effect

• In Triode region the channel has a uniform depth:

$$C_{gs} = C_{gd} = \frac{1}{2} WLC_{ox}$$

• In saturation region: Channel is pinched off:

$$C_{gs} = \frac{2}{3} WLC_{ox} \qquad \qquad C_{gd} = 0$$

• In the cutoff region:

$$C_{gs} = C_{gd} = 0$$

- Often there is overlap area underneath the gate in the S and D diffusion (n⁺ or P⁺) regions.
 - This adds to Cgs and Cgd



Junction Capacitances

- The two pn junction in MOSFET are reverse biased, so the depletion regions creates junction capacitances
- Junction capacitance in a reverse-biased diode or pn junction is defined by:

$$C_{j} = \frac{C_{j0}}{\left(1 + \frac{V_{R}}{V_{0}}\right)^{m}} \qquad \frac{1}{3} \le m \le \frac{1}{2} \qquad C_{j} = \frac{C_{j0}}{\sqrt{1 + \frac{V_{R}}{V_{0}}}}$$

• Where V0 is the junction built-in voltage, Cj0 is the value of Cj when zero voltage is applied and m is the grading coefficient



Junction Capacitances

• The two junction capacitances in MOSFET are:

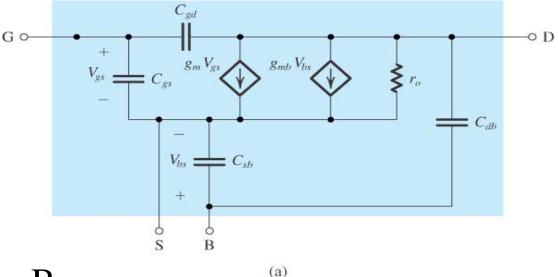
$$C_{sb} = \frac{C_{sb0}}{\sqrt{1 + \frac{V_{SB}}{V_0}}} \qquad \qquad C_{db} = \frac{C_{db0}}{\sqrt{1 + \frac{V_{DB}}{V_0}}}$$

- Assuming m=1/2
- V0 is the junction built-in voltage (0.6 to 0.8 V)
- Csb0 is the value of Csb at VSB=0
- Cdb0 is the value of Cdb at VDB=0
- Formulas are for small-signal operation

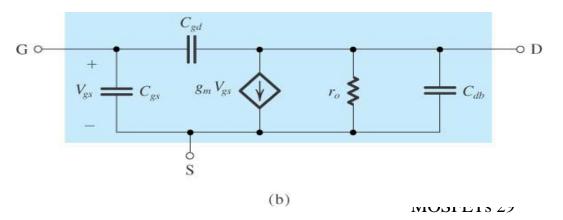


High-Frequency MOSFET Model

• Complete Model used in SPICE (Fig. 4.47):

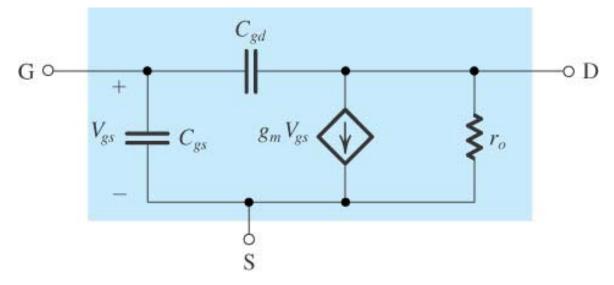


• When S is connected to B:



High-Frequency MOSFET Model

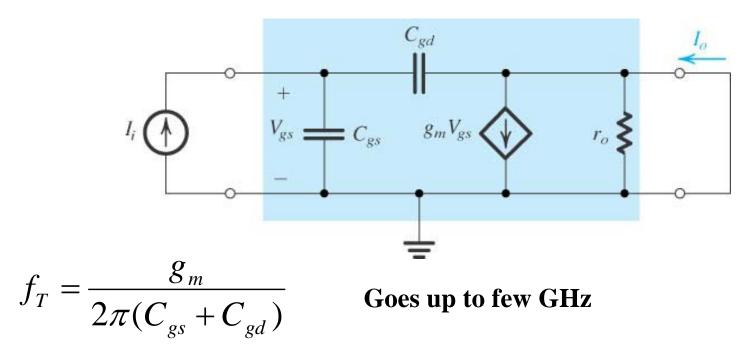
• Capacitance C_{db} is usually neglected and for hand calculations and circuit solutions the following model is used



• Note: Hybrid- π model is used

MOSFET Unity-Gain Frequency

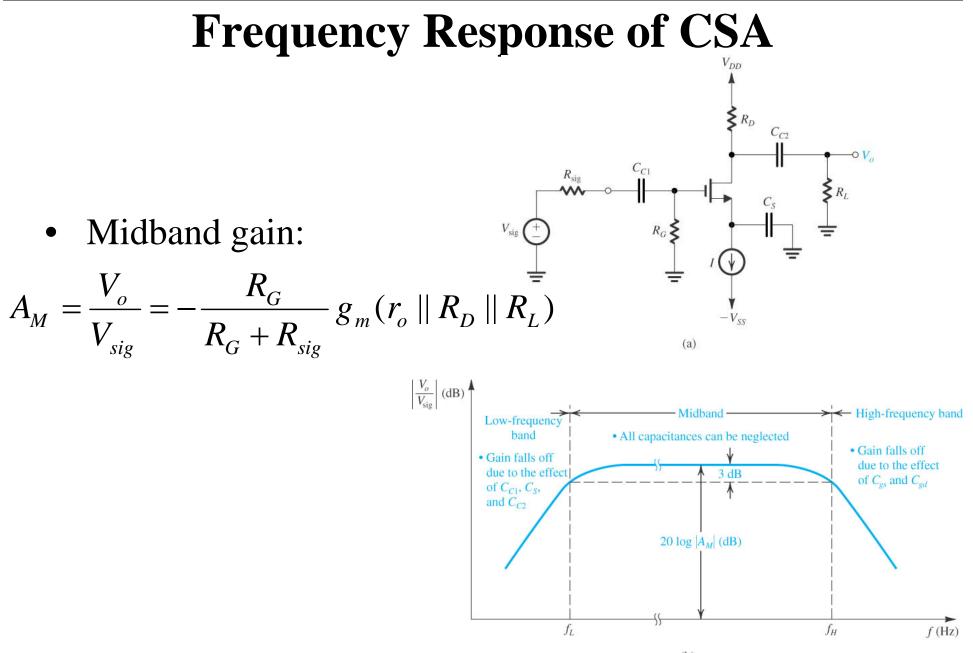
- Unity-gain frequency, f_T , is a figure of merit for high-frequency operation.
- It is defined as the frequency at which the short circuit current gain in the Common Source amplifier is 1.



Frequency Response of CSA

- Gain expressions derived previously were assumed to be independent of frequency.
- In reality gain is constant only over the midband frequencies
- The midband gains are the gain relations we found earlier
- Low frequency falloff is due to coupling and bypass capacitors
- High frequency gain falloff is due to internal capacitances.





High-Frequency Response (CSA)

- f_H and f_L are frequencies at which gain is 3 dB lower than the midband value
- 3dB bandwidth is:

$$BW \equiv f_H - f_L$$

- $BW \cong f_H$ • If $f_I \ll f_H$ then
- Another figure of merit for an amplifier is gain-bandwidth ${\color{black}\bullet}$ product

$$GB \equiv \left| A_{M} \right| BW$$

D

 $r_o \lesssim$

 R_D

 R'_{i}

 R_L

High-Frequency Response (CSA)

 $R_{\rm sig}$

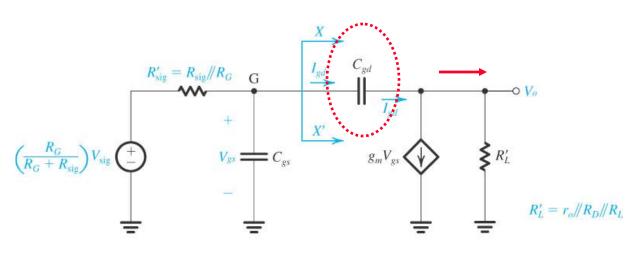
~~~

 $V_{\rm sig}$ 

 $R_G$ 

• CSA

• Using Thevenin Theorem



S

(a)

 $g_m V_{gs}$ 

G

 $= C_{gs}$ 

 $R'_L$ 

### **High-Frequency Response (CSA)**

• Lowpass STC circuit  $R'_{sig}$  G  $V_o = -g_m R'_L$ 

 $= C_{es}$ 

Miller Effect

• Corner frequency

$$\omega_{H} = \omega_{0} = \frac{1}{C_{in}R_{sig}'} = \frac{1}{(C_{gs} + C_{eq})R_{sig}'}$$

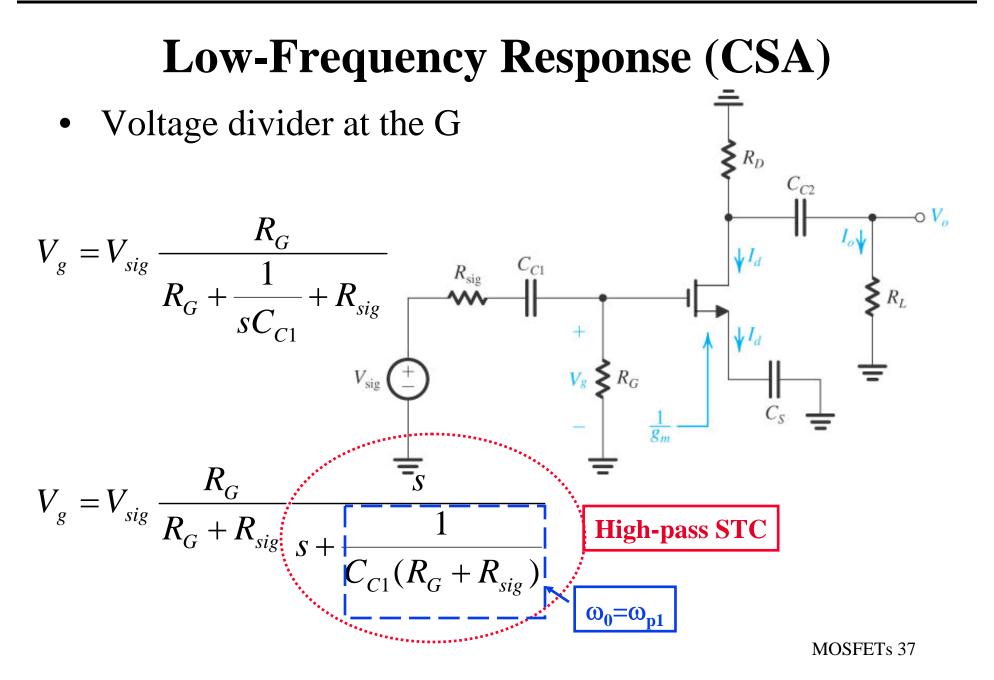
 $C_{eq} = C_{gd} \left( 1 + g_m R_L' \right)$ 

 $g_m V_{es}$ 

• High-frequency gain of CSA

 $\left(\frac{R_G}{R_G + R_{\rm sig}}\right) V_{\rm sig}$ 

$$\frac{V_o}{V_{sig}} = \frac{A_M}{1 + \frac{s}{\omega_H}} = -\frac{R_G}{R_G + R_{sig}} (g_m R'_L) \frac{1}{1 + \frac{s}{\omega_H}}$$



### Low-Frequency Response (CSA)

- Two other high-pass factors are due to:
  - Source bypass capacitance
  - Load coupling capacitance

$$\omega_{p2} = \frac{g_m}{C_s}$$
$$\omega_{p3} = \frac{1}{C_{C2}(R_D + R_L)}$$

• Low-frequency transfer function or low-frequency gain of CSA

$$\frac{V_o}{V_{sig}} = -\frac{R_G}{R_G + R_{sig}} (g_m R_D \parallel R_L) \frac{s}{s + \omega_{P1}} \frac{s}{s + \omega_{P2}} \frac{s}{s + \omega_{P3}}$$

## Low-Frequency Response (CSA)

- To find the time constant for poles  $f_{p1}$ ,  $f_{p2}$  and  $f_{p3}$ 
  - Set source to zero
  - Consider each C separately (others are short circuit)
  - Find the total resistance seen between the two terminals of C  $\left|\frac{V_o}{V_{sig}}\right|^{(dB)}$

